

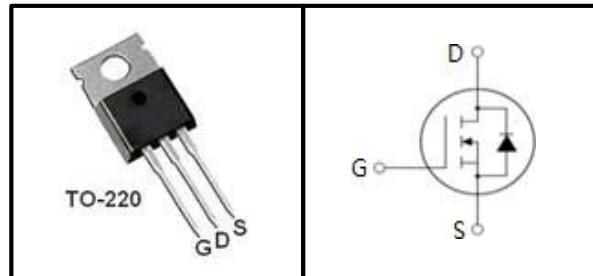
100V N-Channel MOSFET

FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information

| Device | Package | Marking |
|---------|---------|---------|
| MP70N10 | TO-220 | 70N10 |

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------------------|
| | | TO-220 | |
| Drain-Source Voltage ($V_{GS} = 0\text{V}$) | V_{DSS} | 100 | V |
| Continuous Drain Current | I_D | 70 | A |
| Pulsed Drain Current (note1) | I_{DM} | Figure 6 | A |
| Gate-Source Voltage | V_{GSS} | ± 20 | V |
| Single Pulse Avalanche Energy (note2) | E_{AS} | 1943 | mJ |
| Avalanche Current (note1) | I_{AR} | 32 | A |
| Repetitive Avalanche Energy (note1) | E_{AR} | 36 | mJ |
| Power Dissipation ($T_C = 25^\circ\text{C}$) | P_D | 200 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 to 175 | $^\circ\text{C}$ |

Thermal Resistance

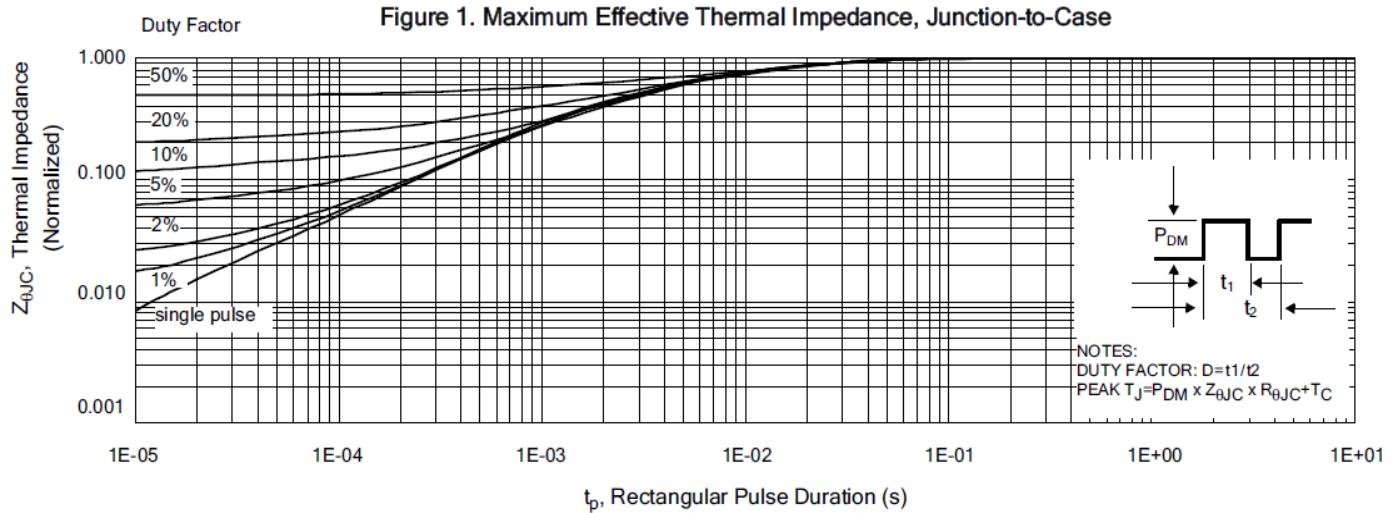
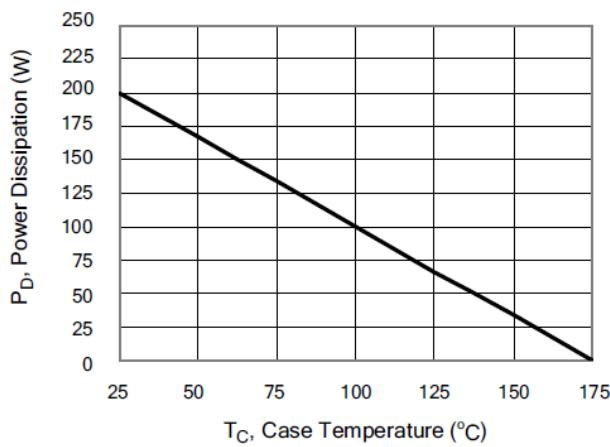
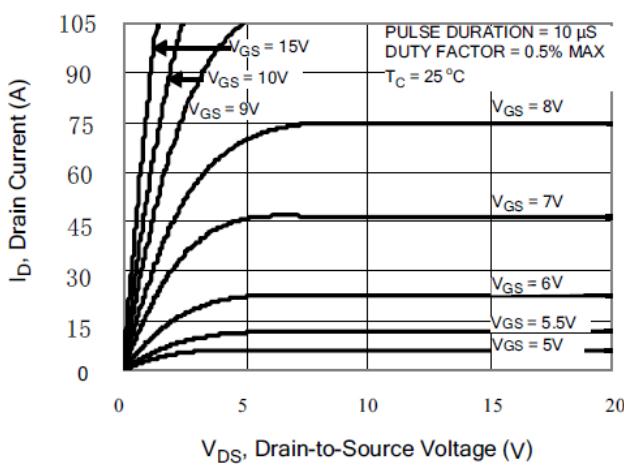
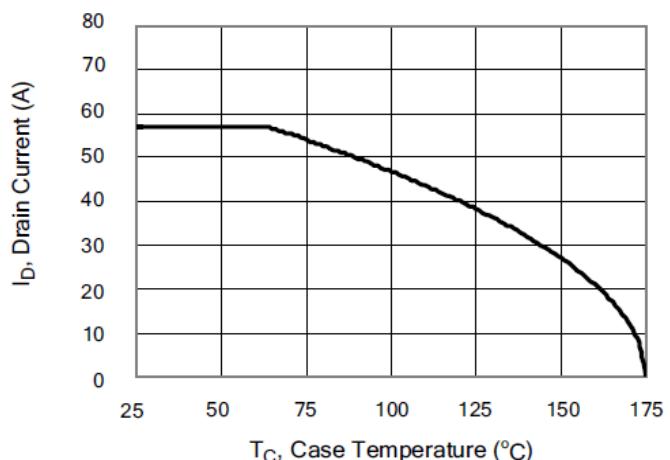
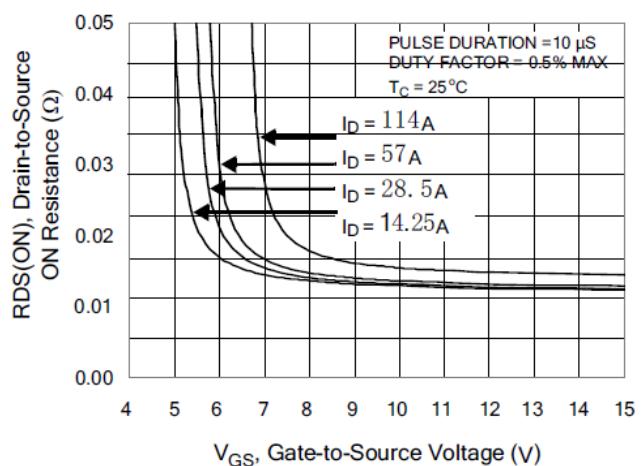
| Parameter | Symbol | Value | Unit |
|---|------------|--------|---------------------------|
| | | TO-220 | |
| Thermal Resistance, Junction-to-Case | R_{thJC} | 0.75 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 62 | |

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Value | | | Unit |
|--|-----------------------------|--|-------|------|------|------------------|
| | | | Min. | Typ. | Max. | |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{GS} = 0V, I_D = 250\mu\text{A}$ | 100 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 100V, V_{GS} = 0V, T_J = 25^\circ\text{C}$ | -- | -- | 1 | μA |
| | | $V_{DS} = 80V, V_{GS} = 0V, T_J = 125^\circ\text{C}$ | -- | -- | 100 | |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = +20V, V_{DS}=0V$ | -- | -- | 100 | nA |
| | | $V_{GS}=-20V, V_{DS}=0V$ | -- | -- | -100 | |
| Gate-Source Threshold Voltage | $V_{GS(\text{th})}$ | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ | 2.0 | -- | 4.0 | V |
| Drain-Source On-Resistance (Note3) | $R_{DS(\text{on})}$ | $V_{GS} = 10V, I_D = 28\text{A}$ | -- | 17 | 21 | $\text{m}\Omega$ |
| Forward Transconductance | g_{fs} | $V_{DS} = 10V, I_D = 28\text{A}$ | | 85 | | S |
| Dynamic | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0\text{MHz}$ | -- | 2700 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 610 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 260 | -- | |
| Total Gate Charge | Q_g | $V_{DD} = 50V, I_D = 28\text{A},$ $V_{GS} = 0 \text{ to } 10V$ | -- | 60 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 15 | -- | |
| Gate-Drain Charge | Q_{gd} | | -- | 45 | -- | |
| Turn-on Delay Time | $t_{d(\text{on})}$ | $V_{DD} = 50V,$ $I_D = 28\text{A},$ $V_{GS} = 10V$ $R_G = 2.5 \Omega$ | -- | 20 | -- | ns |
| Turn-on Rise Time | t_r | | -- | 28 | -- | |
| Turn-off Delay Time | $t_{d(\text{off})}$ | | -- | 65 | -- | |
| Turn-off Fall Time | t_f | | -- | 15 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I_s | $T_C = 25^\circ\text{C}$ | -- | -- | 70 | A |
| Pulsed Diode Forward Current | I_{SM} | | -- | -- | 230 | |
| Body Diode Voltage | V_{SD} | $T_J = 25^\circ\text{C}, I_{SD} = 28\text{A}, V_{GS} = 0V$ | -- | -- | 1.5 | V |
| Reverse Recovery Time | t_{rr} | $V_{GS} = 0V, I_s = 28\text{A},$ $di_F/dt = 100\text{A}/\mu\text{s}$ | -- | 195 | -- | ns |
| Reverse Recovery Charge | Q_{rr} | | -- | 107 | -- | μC |

Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 30\text{A}, V_{DD} = 50V, R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 2. Maximum Power Dissipation vs Case Temperature

Figure 4. Typical Output Characteristics

Figure 3. Maximum Continuous Drain Current vs Case Temperature

Figure 5. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current


Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 6. Maximum Peak Current Capability

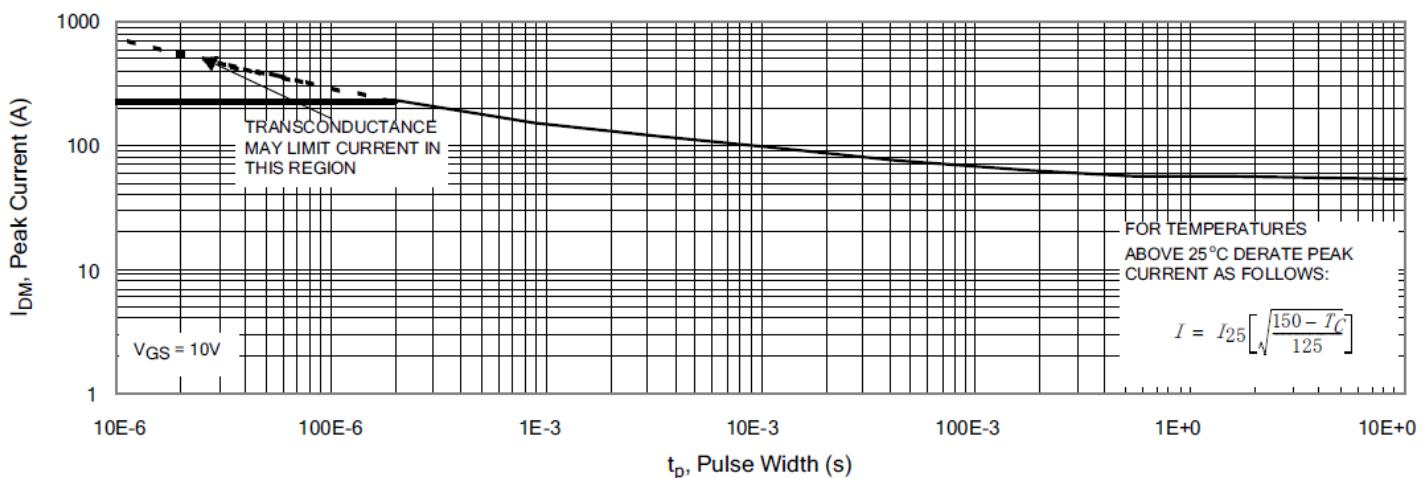


Figure 7. Typical Transfer Characteristics

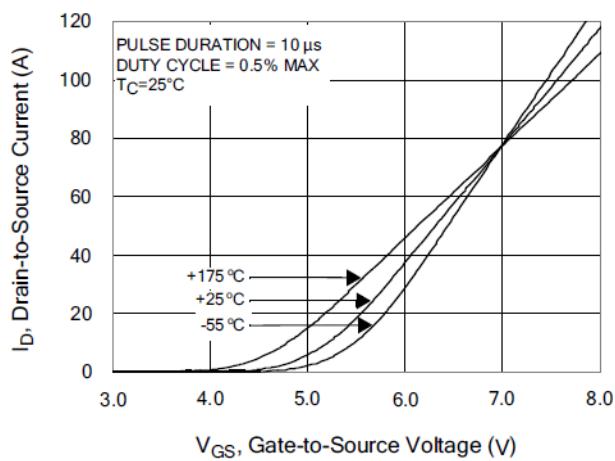


Figure 9. Typical Drain-to-Source ON Resistance vs Drain Current

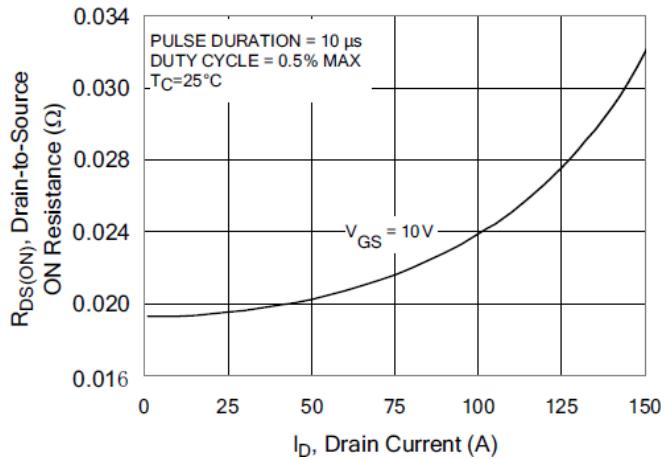


Figure 8. Unclamped Inductive Switching Capability

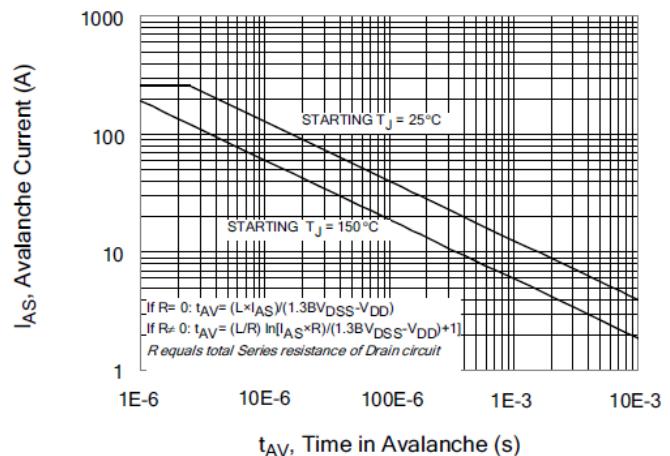
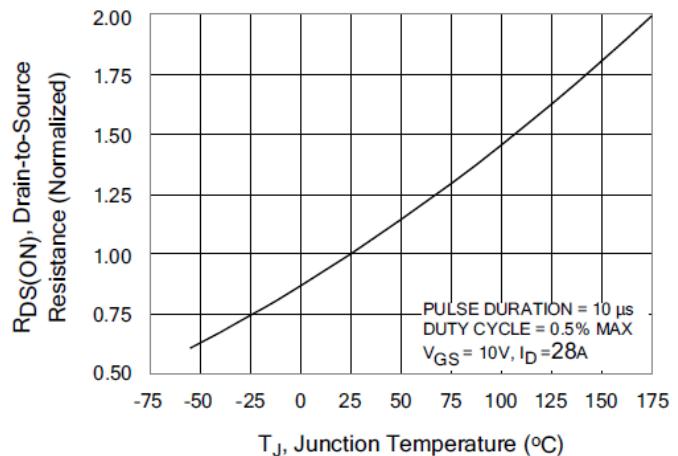


Figure 10. Typical Drain-to-Source ON Resistance vs Junction Temperature



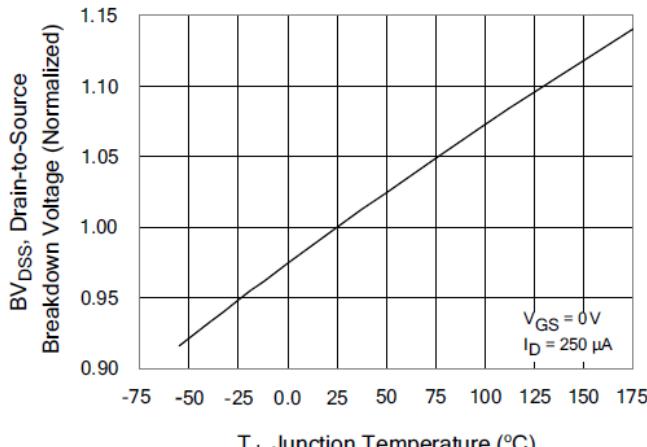
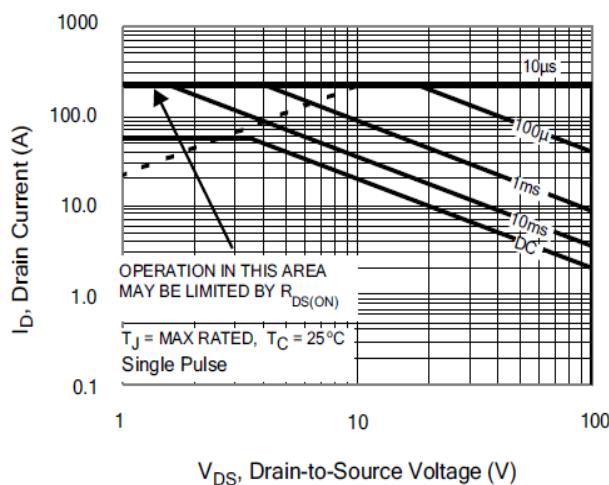
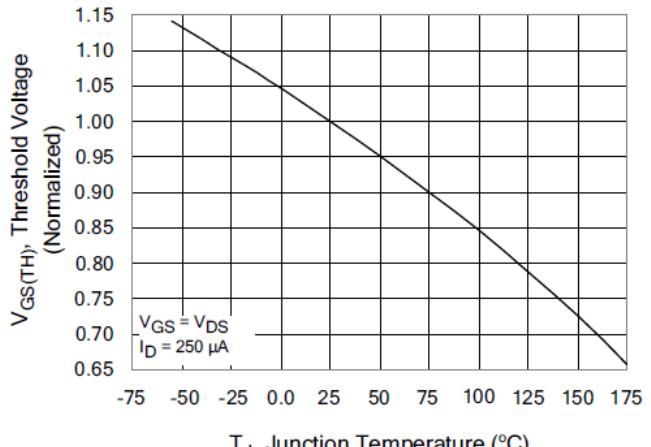
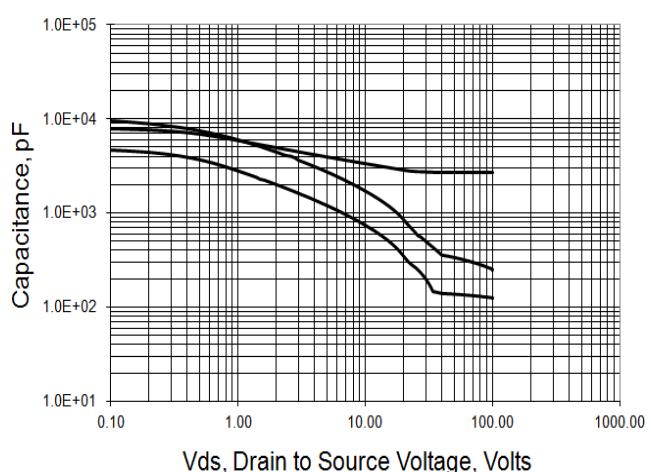
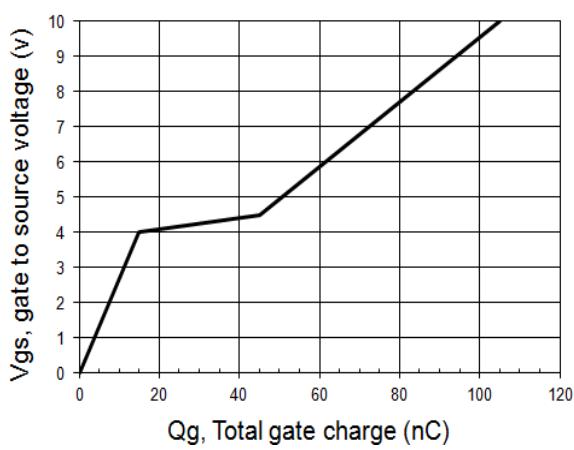
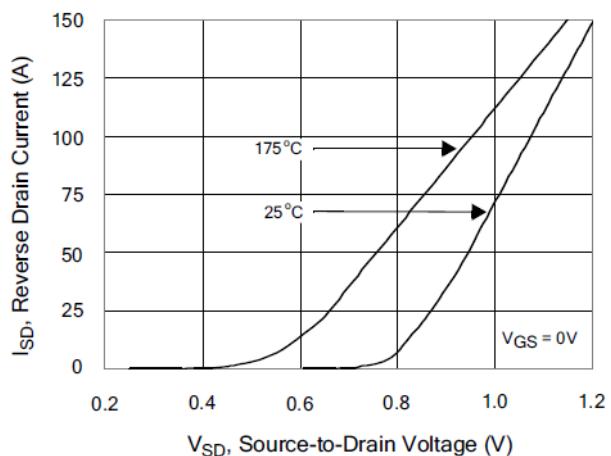
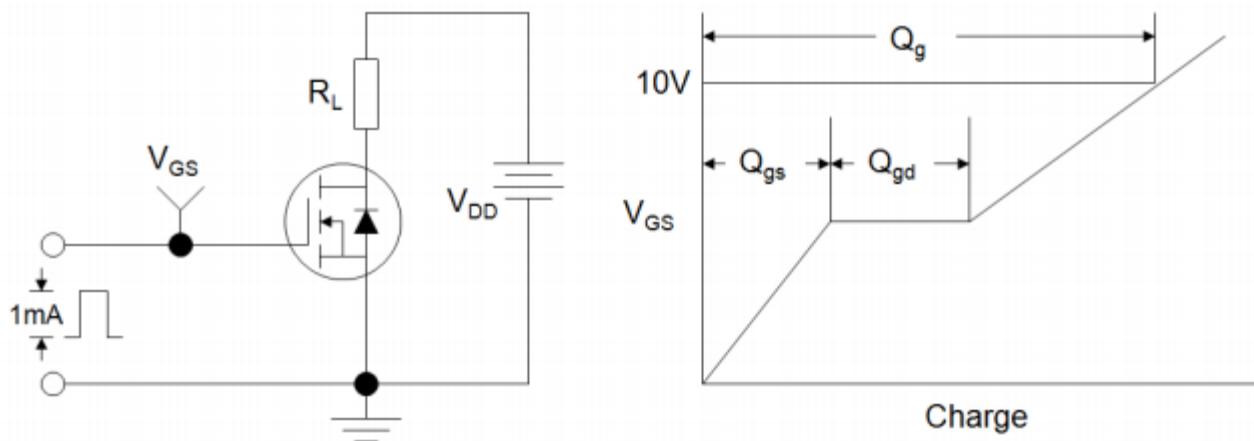
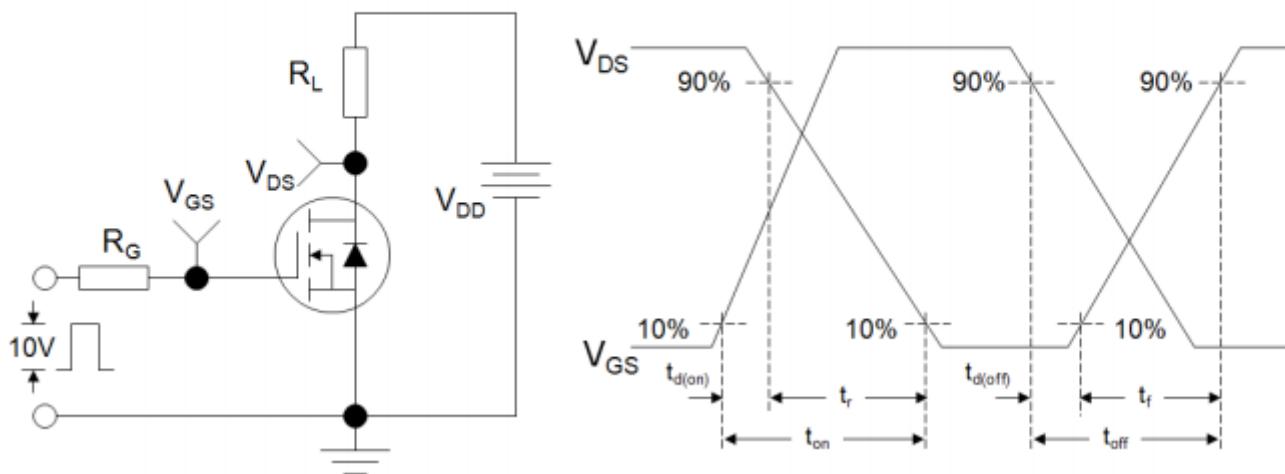
Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted
Figure 11. Typical Breakdown Voltage vs Junction Temperature

Figure 13. Maximum Forward Bias Safe Operating Area

Figure 12. Typical Threshold Voltage vs Junction Temperature

Figure 14. Capacitance vs V_{ds}

Figure 15 .Typical Gate Charge

Figure 16. Typical Body Diode Transfer Characteristics


Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform
